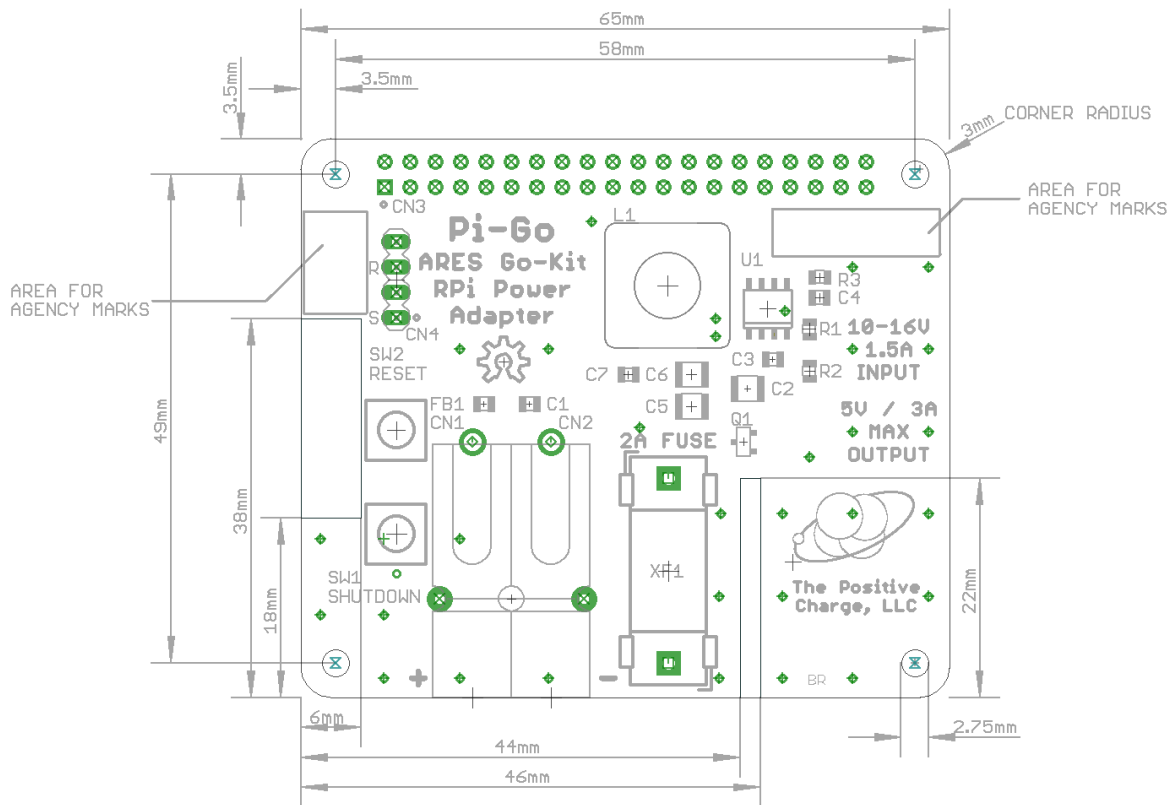


The Positive Charge Pi-Go Rev A – 2015-08-11

Fabrication Details



LAYER-STACK	Sym	Nº	Mils	MM	Qty	Plated
01-16	+	1	20	0.51	32	YES
01-20	x	2	39	1.00	46	YES
	□	3	56	1.42	2	YES
	◇	4	70	1.78	2	YES
	⊗	5	108	2.75	4	NOT

Licensed under the TAPR Open Hardware License (www.tapr.org/OHL)

Board dimensions

- Dimensions in mm:
- Rounded corners = 3mm diameter, 4 places
- Milled slots
 - 20mm x 6mm on left edge
 - 2mm x 22mm on bottom edge

The Positive Charge Pi-Go Rev A – 2015-08-11

Fabrication Details

Notes:

- Board specifications for selected service level take precedence over these notes.
 - Material: FR-4
 - 1oz Copper External Layer
 - Thickness Tolerance ± 0.0061 "
 - Solder Mask: Standard Green, SMOBC
 - Vendor shall stamp agency marks on each board as required
 - Silkscreen Color = White, Component layer only
 - All holes size shall be located within 0.003" (0.08mm) diameter of true position from location shown on master pattern.
 - Finished hole size tolerance: ± 0.003 " (± 0.08 mm)
 - Front-to-Back layer registration to be within 0.003" (0.08mm)
 - Board outline shall conform to supplied Gerber data within 0.010" (0.25mm)
 - All internal corners 0.040" (1.01mm) of radius maximum

Board Stack-up – Use standard for service level, or:

All dimensions in inches unless otherwise noted:

Stack-up	Thickness	Tolerance (\pm)	Layer file ext.	Notes
Layer 1	0.0017	0.0004	cmp	Top Layer
Laminate Core	0.0580	0.0025		
Layer 16	0.0017	0.0004	sol	Bottom Layer
Overall	0.0614	0.0061		